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What is "Embedded - Microcontrollers"?

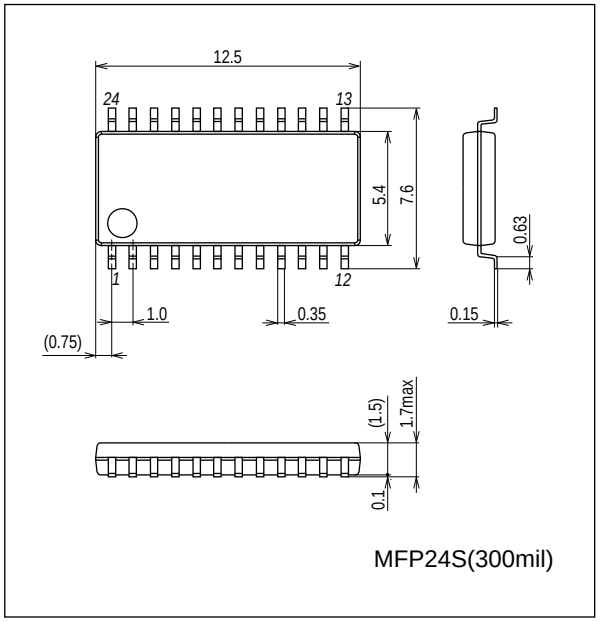
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	-
Core Size	8-Bit
Speed	12MHz
Connectivity	SIO, UART/USART
Peripherals	LVD, POR, WDT
Number of I/O	21
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-LFSOP (0.173", 4.40mm Width)
Supplier Device Package	24-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/sanyo-denki-sanups-products/lc87f2r04au-ssop-h

Package Dimensions

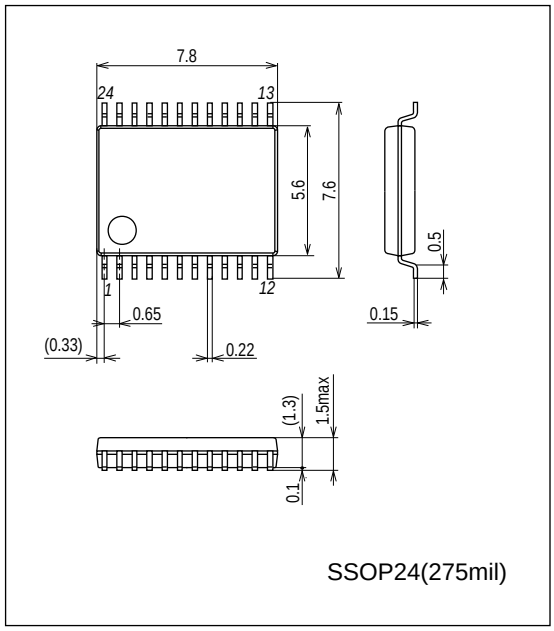
unit : mm (typ)
3112B (discontinued)



MFP24S(300mil)

Package Dimensions

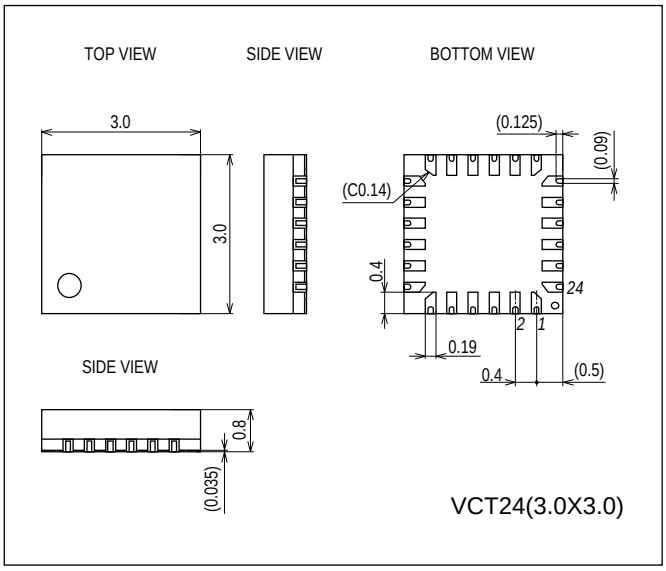
unit : mm (typ)
3175C (build-to-order)



SSOP24(275mil)

Package Dimensions

unit : mm (typ)
3366 (build-to-order)



VCT24(3.0X3.0)

■Minimum Bus Cycle
- 83.3ns (12MHz at V_{DD}=2.7V to 5.5V)
- 100ns (10MHz at V_{DD}=2.2V to 5.5V)

Note: The bus cycle time here refers to the ROM read speed.

■Minimum Instruction Cycle Time
- 250ns (12MHz at V_{DD}=2.7V to 5.5V)
- 300ns (10MHz at V_{DD}=2.2V to 5.5V)

■Ports

- Normal withstand voltage I/O ports
  Ports whose I/O direction can be designated in 1-bit units 11(P1n, P20, P21, P70)
  Ports whose I/O direction can be designated in 4-bit units 8 (P0n)
- Dedicated oscillator ports/input ports 2 (CF1, CF2)
- Reset pin 1 ($\overline{RES}$)
- Power pins 2 ($V_{SS}1$, $V_{DD}1$)

■Timers

- Timer 0: 16-bit timer/counter with a capture register.
  Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) × 2 channels
  Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)
  + 8-bit counter (with an 8-bit capture register)
  Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)
  Mode 3: 16-bit counter (with a 16-bit capture register)
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)

■SIO

- SIO1: 8-bit asynchronous/synchronous serial interface
  Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
  Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
  Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
  Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

■AD Converter: 12 bits/8 bits × 8 channels

- 12/8 bits AD converter resolution selectable

■Remote Control Receiver Circuit (sharing pins with P73, INT3, and T0IN)

- Noise rejection function (noise filter time constant selectable from 1 tCYC/32 tCYC/128 tCYC)

■Watchdog Timer

- External RC watchdog timer
- Interrupt and reset signals selectable

■Interrupts

- 12 sources, 8 vector addresses
  1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
  2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4
4	0001BH	H or L	INT3
5	00023H	H or L	T0H
6	0002BH	H or L	None
7	00033H	H or L	None
8	0003BH	H or L	SIO1
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.

■Subroutine Stack Levels: 64levels (The stack is allocated in RAM.)

■Development Tools

- On-chip debugger: TCB87 TypeB+LC87F2R04A
  : TCB87 TypeC (3 wire version) +LC87F2R04A

■Programming Boards

Package	Programming boards
MFP24S(300mil)	W87F2GM
SSOP24(225mil)	W87F2GS
SSOP24(275mil)	build-to-order
VCT24	build-to-order

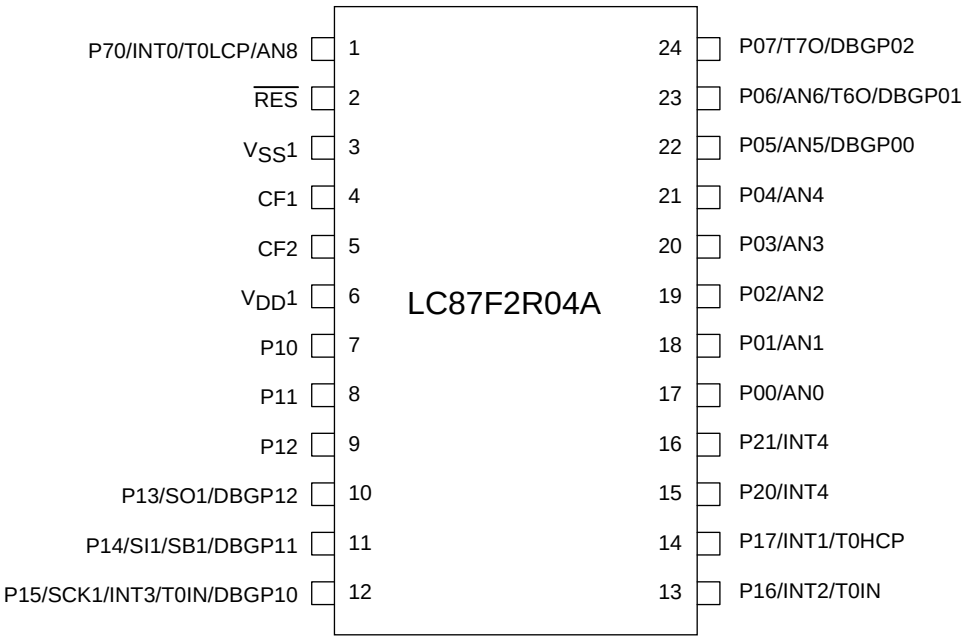
■Flash ROM Programmer

Maker		Model	Supported Version	Device
Flash Support Group, Inc. (FSG)	Single	AF9708 AF9709/AF9709B/AF9709C (including Ando Electric Co., Ltd. models)	Rev 03.11 or later	LC87F2L08A
	Ganged	AF9723/AF9723B(Main unit) (including Ando Electric Co., Ltd. models)	-	-
		AF9833(Unit) (including Ando Electric Co., Ltd. models)	-	-
Flash Support Group, Inc. (FSG) + Our company (Note 1)	Onboard single/ganged	AF9101/AF9103(Main unit) (FSG)	(Note 2)	-
		SIB87(Interface driver) (Our company)		
Our company	Single/ganged	SKK/SKK Type B (SANYO FWS)	Application version 1.05 or later Chip data version 2.22 or later	LC87F2R04A
	Onboard single/ganged	SKK-DBG Type B (SANYO FWS)		

For information about AF-Series:
Flash Support Group, Inc.
TEL: +81-53-459-1050
E-mail: sales@j-fsg.co.jp

Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from Our company (SIB87) together
can give a PC-less, standalone on-board-programming capabilities.
Note2: It needs a special programming devices and applications depending on the use of programming environment.
Please ask FSG or Our company for the information.

Pin Assignment

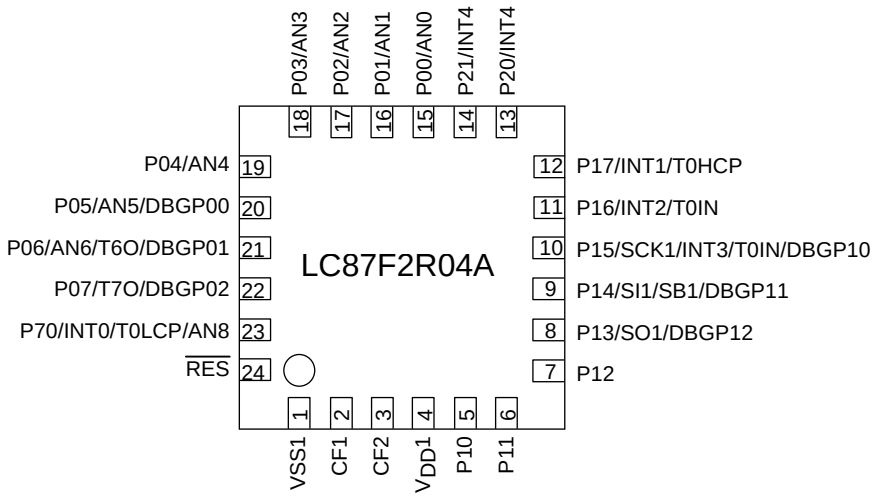


Top view

MFP24S(300mil) “Lead-/Halogen-free Type” (discontinued)
SSOP24(225mil) “Lead-/Halogen-free Type”
SSOP24(275mil) “Lead-/Halogen-free Type” (build-to-order)

MFP24S SSOP24	NAME
1	P70/INT0/T0LCP/AN8
2	$\overline{\text{RES}}$
3	$V_{SS}1$
4	CF1
5	CF2
6	$V_{DD}1$
7	P10
8	P11
9	P12
10	P13/SO1/DBGP12
11	P14/SI1/SB1/DBGP11
12	P15/SCK1/INT3/T0IN/DBGP10

MFP24S SSOP24	NAME
13	P16/INT2/T0IN
14	P17/INT1/T0HCP
15	P20/INT4
16	P21/INT4
17	P00/AN0
18	P01/AN1
19	P02/AN2
20	P03/AN3
21	P04/AN4
22	P05/AN5/DBGP00
23	P06/AN6/T6O/DBGP01
24	P07/T7O/DBGP02



Top view

VCT24(3.0×3.0) “Lead-/Halogen-free Type” (build-to-order)

VCT24	NAME
1	$V_{SS}1$
2	CF1
3	CF2
4	VDD1
5	P10
6	P11
7	P12
8	P13/SO1/DBGP12
9	P14/SI1/SB1/DBGP11
10	P15/SCK1/INT3/T0IN/DBGP10
11	P16/INT2/T0IN
12	P17/INT1/T0HCP

VCT24	NAME
13	P20/INT4
14	P21/INT4
15	P00/AN0
16	P01/AN1
17	P02/AN2
18	P03/AN3
19	P04/AN4
20	P05/AN5/DBGP00
21	P06/AN6/T6O/DBGP01
22	P07/T7O/DBGP02
23	P70/INT0/T0LCP/AN8
24	$\overline{RES}$

Pin Description

<table>
<tr><th>Pin Name</th><th>I/O</th><th>Description</th><th>Option</th></tr>
<tr><td>$V_{SS}1$</td><td>-</td><td>- power supply pins</td><td>No</td></tr>
<tr><td>$V_{DD}1$</td><td>-</td><td>+ power supply pin</td><td>No</td></tr>
<tr><td>Port 0
P00 to P07</td><td>I/O</td><td>• 8-bit I/O port
• I/O specifiable in 4-bit units
• Pull-up resistors can be turned on and off in 4-bit units.
• HOLD reset input
• Port 0 interrupt input
• Pin functions
P06: Timer 6 toggle output
P07: Timer 7 toggle output
P00(AN0) to P06(AN6): AD converter input
P05(DBGP00) to P07(DBGP02): On-chip debugger 0 port</td><td>Yes</td></tr>
<tr><td>Port 1
P10 to P17</td><td>I/O</td><td>• 8-bit I/O port
• I/O specifiable in 1-bit units
• Pull-up resistors can be turned on and off in 1-bit units.
• Pin functions
P13: SIO1 data output
P14: SIO1 data input/bus I/O
P15: SIO1 clock I/O/INT3 input (with noise filter)/timer 0 event input/timer 0H capture input
P16: INT2 input/HOLD reset input/timer 0 event input/timer 0L capture input
P17: INT1 input/HOLD reset input/timer 0H capture input
P15(DBGP10) to P13(DBGP12): On-chip debugger 1 port
Interrupt acknowledge types
<table>
<tr><th></th><th>Rising</th><th>Falling</th><th>Rising & Falling</th><th>H level</th><th>L level</th></tr>
<tr><td>INT1</td><td>enable</td><td>enable</td><td>disable</td><td>enable</td><td>enable</td></tr>
<tr><td>INT2</td><td>enable</td><td>enable</td><td>enable</td><td>disable</td><td>disable</td></tr>
<tr><td>INT3</td><td>enable</td><td>enable</td><td>enable</td><td>disable</td><td>disable</td></tr>
</table></td><td>Yes</td></tr>
<tr><td>Port 2
P20 to P21</td><td>I/O</td><td>• 2-bit I/O port
• I/O specifiable in 1-bit units
• Pull-up resistors can be turned on and off in 1-bit units.
• Pin functions
P20 to P21: INT4 input/HOLD reset input/timer 0L capture input/ timer 0H capture input
Interrupt acknowledge types
<table>
<tr><th></th><th>Rising</th><th>Falling</th><th>Rising & Falling</th><th>H level</th><th>L level</th></tr>
<tr><td>INT4</td><td>enable</td><td>enable</td><td>enable</td><td>disable</td><td>disable</td></tr>
</table></td><td>Yes</td></tr>
<tr><td>Port 7
P70</td><td>I/O</td><td>• 1-bit I/O port
• I/O specifiable in 1-bit units
• Pull-up resistors can be turned on and off in 1-bit units.
• Pin functions
P70: INT0 input/HOLD reset input/timer 0L capture input/watchdog timer output
P70(AN8): AD converter input
Interrupt acknowledge types
<table>
<tr><th></th><th>Rising</th><th>Falling</th><th>Rising & Falling</th><th>H level</th><th>L level</th></tr>
<tr><td>INT0</td><td>enable</td><td>enable</td><td>disable</td><td>enable</td><td>enable</td></tr>
</table></td><td>No</td></tr>
<tr><td>$\overline{RES}$</td><td>I/O</td><td>External reset Input/internal reset output</td><td>No</td></tr>
<tr><td>CF1</td><td>I</td><td>• Ceramic resonator oscillator input pin
• Pin function
General-purpose input port</td><td>No</td></tr>
<tr><td>CF2</td><td>I/O</td><td>• Ceramic resonator oscillator output pin
• Pin function
General-purpose input port</td><td>No</td></tr>
</table>

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.
Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P21	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable

Note 1: The control of the presence or absence of the programmable pull-up resistors for port 0 and the switching between low-and high-impedance pull-up connection is exercised in nibble (4-bit) units (P00 to 03 or P04 to 07).

User Option Table

Option Name	Option Type	Mask version *1	Flash Version	Option Selected in Units of	Option Selection
Port output type	P00 to P07	O	O	1 bit	CMOS
					Nch-open drain
	P10 to P17	O	O	1 bit	CMOS
					Nch-open drain
	P20 to P21	O	O	1 bit	CMOS
					Nch-open drain
Program start address	-	× *2	O	-	00000h
					01E00h
Low-voltage detection reset function	Detect function	O	O	-	Enable: Use
					Disable: Not Used
	Detect level	O	O	-	7-level
Power-on reset function	Power-On reset level	O	O	-	8-level

*1: Mask option selection-No change possible after mask is completed.
*2: Program start address of the mask version is 00000h.

Recommended Unused Pin Connections

Port Name	Recommended Unused Pin Connections	
	Board	Software
P00 to P07	Open	Output low
P10 to P17	Open	Output low
P20 to P21	Open	Output low
P70	Open	Output low
CF1	Pulled low with a 100kΩ resistor or less	General-purpose input port
CF2	Pulled low with a 100kΩ resistor or less	General-purpose input port

On-chip Debugger Pin Connection Requirements

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "RD87 on-chip debugger installation manual" and "LC872000 series on-chip debugger pin connection requirements"

Notes on CF1 and CF2 Pins

- When using as general-purpose input ports
  Since the CF1 and CF2 pins are configured as CF oscillator pins at system reset time, it is necessary to add a current limiting resistor of 1kΩ or greater to the CF2 pin in series when using them as general-purpose input pins.

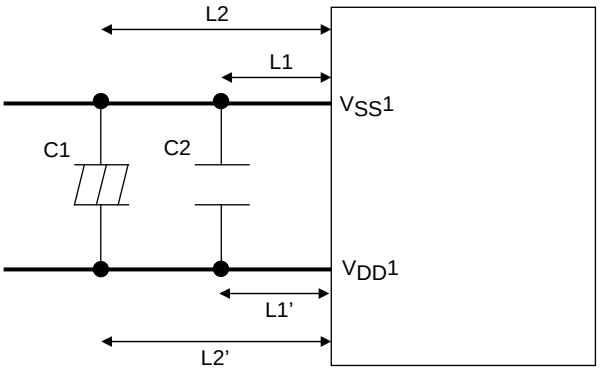
Differences between LC872G00 and LC872R00 Series.

		System Reset Time State	After System Reset is Released
Flash ROM version LC87F2G08A	CF1/XT1	Set high via the internal Rf resistor	CF oscillation state
	CF2/XT2	Set high	CF oscillation state
Mask ROM version LC872G08A	CF1/XT1	Set low via the internal Rf resistor	CF oscillation state
	CF2/XT2	Set low	CF oscillation state
Flash ROM version LC87F2R04A Mask ROM version LC872R04A	CF1	Set low via the internal Rf resistor	CF oscillation state
	CF2	High-impedance (OPEN)	CF oscillation state

Power Pin Treatment Recommendations ($V_{DD}1$, $V_{SS}1$)

Connect bypass capacitors that meet the following conditions between the $V_{DD}1$ and $V_{SS}1$ pins:

- Connect among the $V_{DD}1$ and $V_{SS}1$ pins and bypass capacitors C1 and C2 with the shortest possible heavy lead wires, making sure that the impedances between the both pins and the bypass capacitors are as possible (L1=L1' , L2=L2').
- Connect a large-capacity capacitor C1 and a small-capacity capacitor C2 in parallel. The capacitance of C2 should approximately 0.1μF.



Absolute Maximum Ratings at Ta = 25°C, $V_{SS}1$ = 0V

Parameter		Symbol	Pin/Remarks	Conditions		Specification			
					V_{DD}[V]	min	typ	max	unit
Maximum supply voltage		V_{DD} max	$V_{DD}1$			-0.3		+6.5	V
Input voltage		V_I	CF1, CF2			-0.3		V_{DD}+0.3	
Input/output voltage		V_{IO}	Ports 0, 1, 2 P70			-0.3		V_{DD}+0.3	
High level output current	Peak output current	IOPH	Ports 0, 1, 2	CMOS output select Per 1 applicable pin		-10			mA
	Mean output current (Note 1-1)	IOMH	Ports 0, 1, 2	CMOS output select Per 1 applicable pin		-7.5			
	Total output current	ΣIOAH(1)	P10 to P14	Total of all applicable pins		-20			
		ΣIOAH(2)	P15 to P17 Ports 0, 2	Total of all applicable pins		-20			
		ΣIOAH(3)	Ports 0, 1, 2	Total of all applicable pins		-25			
Low level output current	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2	Per 1 applicable pin				20	
		IOPL(2)	P00, P01	Per 1 applicable pin				30	
		IOPL(3)	P70	Per 1 applicable pin				10	
	Mean output current (Note 1-1)	IOML(1)	P02 to P07 Ports 1, 2	Per 1 applicable pin				15	
		IOML(2)	P00, P01	Per 1 applicable pin				20	
		IOML(3)	P70	Per 1 applicable pin				7.5	
	Total output current	ΣIOAL(1)	P10 to P14	Total of all applicable pins				50	
		ΣIOAL(2)	Ports 0, 2 P15 to P17	Total of all applicable pins				60	
		ΣIOAL(3)	Ports 0, 1, 2	Total of all applicable pins				70	
		ΣIOAL(4)	P70	Total of all applicable pins				7.5	
Power Dissipation		Pd max(1)	MFP24S(300mil))	Ta=-40 to +85°C Package only				129	mW
		Pd max(2)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				229	
		Pd max(3)	SSOP24(225mil)	Ta=-40 to +85°C Package only				111	
		Pd max(4)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				334	
Operating ambient Temperature		Topr				-40		+85	°C
Storage ambient temperature		Tstg				-55		+125	

Note 1-1: The mean output current is a mean value measured over 100ms.

Note 1-2: SEMI standards thermal resistance board (size: 76.1×114.3×1.6tmm, glass epoxy) is used.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Allowable Operating Conditions at Ta = -40°C to +85°C, $V_{SS}1$ = 0V

Parameter	Symbol	Pin/Remarks	Conditions	V_{DD}[V]	Specification min	typ	max	unit
Operating supply voltage (Note 2-1)	$V_{DD}(1)$	$V_{DD}1$	0.245µs ≤ tCYC ≤ 200µs		2.7		5.5	V
	$V_{DD}(2)$		0.294µs ≤ tCYC ≤ 200µs		2.2		5.5	
Memory sustaining supply voltage	VHD	$V_{DD}1$	RAM and register contents sustained in HOLD mode.		1.6			
High level input voltage	$V_{IH}(1)$	Ports 1, 2 P70 port input/ interrupt side		2.2 to 5.5	$0.3V_{DD}+0.7$		V_{DD}	
	$V_{IH}(2)$	Port 0		2.2 to 5.5	$0.3V_{DD}+0.7$		V_{DD}	
	$V_{IH}(3)$	Port 70 watchdog timer side		2.2 to 5.5	$0.9V_{DD}$		V_{DD}	
	$V_{IH}(4)$	CF1, $\overline{RES}$		2.2 to 5.5	$0.75V_{DD}$		V_{DD}	
Low level input voltage	$V_{IL}(1)$	Ports 1, 2, P70 port input/ interrupt side		4.0 to 5.5	V_{SS}		$0.1V_{DD}+0.4$	
				2.2 to 4.0	V_{SS}		$0.2V_{DD}$	
	$V_{IL}(2)$	Port 0		4.0 to 5.5	V_{SS}		$0.15V_{DD}+0.4$	
				2.2 to 4.0	V_{SS}		$0.2V_{DD}$	
	$V_{IL}(3)$	Port 70 watchdog timer side		2.2 to 5.5	V_{SS}		$0.8V_{DD}-1.0$	
	$V_{IL}(4)$	CF1, $\overline{RES}$		2.2 to 5.5	V_{SS}		$0.25V_{DD}$	
Instruction cycle time (Note 2-1)	tCYC (Note 2-2)			2.7 to 5.5	0.245		200	µs
				2.2 to 5.5	0.294		200	
External system clock frequency	FEXCF	CF1	• CF2 pin open • System clock frequency division ratio=1/1 • External system clock duty=50±5%	2.7 to 5.5	0.1		12	MHz
				2.2 to 5.5	0.1		10	
			• CF2 pin open • System clock frequency division ratio=1/2 • External system clock duty=50±5%	3.0 to 5.5	0.2		24.4	
Oscillation frequency range (Note 2-3)	FmCF(1)	CF1, CF2	12MHz ceramic oscillation See Fig. 1.	2.7 to 5.5		12		MHz
	FmCF(2)	CF1, CF2	10MHz ceramic oscillation See Fig. 1.	2.2 to 5.5		10		
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation. CF oscillation normal amplifier size selected. (CFLAMP=0) See Fig. 1	2.2 to 5.5		4		
			4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1) See Fig. 1.	2.2 to 5.5		4		
	FmMRC		Frequency variable RC oscillation. 1/2 frequency division ration. (RCCTD=0) (Note 2-4)	2.7 to 5.5	7.6	8.0	8.4	
	FmRC		Internal medium-speed RC oscillation	2.2 to 5.5	0.5	1.0	2.0	

Note 2-1: V_{DD} must be held greater than or equal to 2.2V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Note 2-4: When switching the system clock, allow an oscillation stabilization time of 100µs or longer after the multifrequency RC oscillator circuit transmits from the "oscillation stopped" to "oscillation enabled" state.

Electrical Characteristics at Ta = -40°C to +85°C, $V_{SS}1$ = 0V

Parameter	Symbol	Pin/Remarks	Conditions	V_{DD}[V]	Specification min	typ	max	unit
High level input current	I_{IH}(1)	Ports 0, 1, 2 P70 $\overline{RES}$	Output disabled Pull-up resistor off $V_{IN}=V_{DD}$ (Including output Tr's off leakage current)	2.2 to 5.5			1	µA
	I_{IH}(2)	CF1	$V_{IN}=V_{DD}$	2.2 to 5.5			15	
Low level input current	I_{IL}(1)	Ports 0, 1, 2 P70 $\overline{RES}$	Output disabled Pull-up resistor off $V_{IN}=V_{SS}$ (Including output Tr's off leakage current)	2.2 to 5.5	-1			
	I_{IL}(2)	CF1	$V_{IN}=V_{SS}$	2.2 to 5.5	-15			
High level output voltage	V_{OH}(1)	Ports 0, 1, 2	I_{OH}=-1mA	4.5 to 5.5	V_{DD}-1			V
	V_{OH}(2)		I_{OH}=-0.35mA	2.7 to 5.5	V_{DD}-0.4			
	V_{OH}(3)		I_{OH}=-0.15mA	2.2 to 5.5	V_{DD}-0.4			
Low level output voltage	V_{OL}(1)	Ports 0, 1, 2	I_{OL}=10mA	4.5 to 5.5			1.5	
	V_{OL}(2)		I_{OL}=1.4mA	2.7 to 5.5			0.4	
	V_{OL}(3)		I_{OL}=0.8mA	2.2 to 5.5			0.4	
	V_{OL}(4)	P70	I_{OL}=1.4mA	2.7 to 5.5			0.4	
	V_{OL}(5)		I_{OL}=0.8mA	2.2 to 5.5			0.4	
	V_{OL}(6)	P00, P01	I_{OL}=25mA	4.5 to 5.5			1.5	
	V_{OL}(7)		I_{OL}=4mA	2.7 to 5.5			0.4	
	V_{OL}(8)		I_{OL}=2mA	2.2 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2 P70	V_{OH}=0.9V_{DD} When Port 0 selected low-impedance pull-up.	4.5 to 5.5	15	35	80	kΩ
	Rpu(2)			2.2 to 4.5	18	50	230	
	Rpu(3)	Port 0	V_{OH}=0.9V_{DD} When Port 0 selected high-impedance pull-up.	2.2 to 5.5	100	210	400	
Hysteresis voltage	VHYS(1)	Ports 1, 2 P70 $\overline{RES}$		2.7 to 5.5		0.1V_{DD}		V
	VHYS(2)			2.2 to 5.5		0.07V_{DD}		
Pin capacitance	CP	All pins	For pins other than that under test: $V_{IN}=V_{SS}$ f=1MHz Ta=25°C	2.2 to 5.5		10		pF

AD Converter Characteristics at Ta = -40°C to +85°C, $V_{SS}1$ = 0V

12bits AD Converter Mode

Parameter	Symbol	Pin/Remarks	Conditions		Specification			
				V_{DD}[V]	min	typ	max	unit
Resolution	N	AN0(P00) to AN6(P06), AN8(P70)		2.4 to 5.5		12		bit
Absolute accuracy	ET		(Note 6-1)	2.7 to 5.5			±16	LSB
				2.4 to 5.5			±20	
Conversion time	TCAD		• See Conversion time calculation formulas. (Note 6-2)	4.0 to 5.5	32		115	µs
				2.7 to 5.5	64		115	
				2.4 to 5.5	410		425	
Analog input voltage range	VAIN			2.4 to 5.5	V_{SS}		V_{DD}	V
Analog port input current	IAINH		VAIN=V_{DD}	2.4 to 5.5			1	µA
	IAINL		VAIN=V_{SS}	2.4 to 5.5	-1			

8bits AD Converter Mode

Parameter	Symbol	Pin/Remarks	Conditions		Specification			
				V_{DD}[V]	min	typ	max	unit
Resolution	N	AN0(P00) to AN6(P06) AN8(P70)		2.4 to 5.5		8		bit
Absolute accuracy	ET		(Note 6-1)	2.4 to 5.5			±1.5	LSB
Conversion time	TCAD		• See Conversion time calculation formulas. (Note 6-2)	4.0 to 5.5	20		90	µs
				2.7 to 5.5	40		90	
				2.4 to 5.5	250		265	
Analog input voltage range	VAIN			2.4 to 5.5	V_{SS}		V_{DD}	V
Analog port input current	IAINH		VAIN=V_{DD}	2.4 to 5.5			1	µA
	IAINL		VAIN=V_{SS}	2.4 to 5.5	-1			

Conversion time calculation formulas:

12bits AD Converter Mode: TCAD(Conversion time) = ((52/(AD division ratio))+2)×(1/3)×tCYC

8bits AD Converter Mode: TCAD(Conversion time) = ((32/(AD division ratio))+2)× (1/3)×tCYC

External oscillation (FmCF)	Operating supply voltage range (V_{DD})	System division ratio (SYSDIV)	Cycle time (tCYC)	AD division ratio (ADDIV)	AD conversion time (TCAD)	
					12bit AD	8bit AD
CF-12MHz	4.0V to 5.5V	1/1	250ns	1/8	34.8µs	21.5µs
	3.0V to 5.5V	1/1	250ns	1/16	69.5µs	42.8µs
CF-10MHz	4.0V to 5.5V	1/1	300ns	1/8	41.8µs	25.8µs
	3.0V to 5.5V	1/1	300ns	1/16	83.4µs	51.4µs
CF-4MHz	3.0V to 5.5V	1/1	750ns	1/8	104.5µs	64.5µs
	2.4V to 5.5V	1/1	750ns	1/32	416.5µs	256.5µs

Note 6-1: The quantization error (±1/2LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Power-on Reset (POR) Characteristics at Ta = -40°C to +85°C, $V_{SS}1$= 0V

Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	Specification min	typ	max	unit
POR release voltage	PORRL		• Select from option. (Note 7-1)	1.67V	1.55	1.67	1.79	V
				1.97V	1.85	1.97	2.09	
				2.07V	1.95	2.07	2.19	
				2.37V	2.25	2.37	2.49	
				2.57V	2.45	2.57	2.69	
				2.87V	2.75	2.87	2.99	
				3.86V	3.73	3.86	3.99	
				4.35V	4.21	4.35	4.49	
Detection voltage unknown state	POUKS		• See Fig. 7. (Note 7-2)			0.7	0.95	
Power supply rise time	PORIS		• Power supply rise time from 0V to 1.6V.				100	ms

Note7-1: The POR release level can be selected out of 4 levels only when the LVD reset function is disabled.
Note7-2: POR is in an unknown state before transistors start operation.

Low Voltage Detection Reset (LVD) Characteristics at Ta = -40°C to +85°C, $V_{SS}1$ = 0V

Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	Specification min	typ	max	unit
LVD reset Voltage (Note 8-2)	LVDET		• Select from option. (Note 8-1) (Note 8-3) • See Fig. 8.	1.91V	1.81	1.91	2.01	V
				2.01V	1.91	2.01	2.11	
				2.31V	2.21	2.31	2.41	
				2.51V	2.41	2.51	2.61	
				2.81V	2.71	2.81	2.91	
				3.79V	3.69	3.79	3.89	
				4.28V	4.18	4.28	4.38	
LVD hysteresis width	LVHYS			1.91V		55		mV
				2.01V		55		
				2.31V		55		
				2.51V		55		
				2.81V		60		
				3.79V		65		
				4.28V		65		
Detection voltage unknown state	LVUKS		• See Fig. 8. (Note 8-4)			0.7	0.95	V
Low voltage detection minimum Width (Reply sensitivity)	TLVDW		• LVDET-0.5V • See Fig. 9.		0.2			ms

Note8-1: The LVD reset level can be selected out of 3 levels only when the LVD reset function is enabled.
Note8-2: LVD reset voltage specification values do not include hysteresis voltage.
Note8-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.
Note8-4: LVD is in an unknown state before transistors start operation.

Consumption Current Characteristics at Ta = -40°C to +85°C, $V_{SS}1$ = 0V

Parameter	Symbol	Pin/ Remarks	Conditions	V_{DD}[V]	Specification min	typ	max	unit
Normal mode consumption current (Note 9-1) (Note 9-2)	IDDOP(1)	$V_{DD}1$	• FmCF=12MHz ceramic oscillation mode • System clock set to 12MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 5.5		6.1	10	mA
				2.7 to 3.6		3.7	6.4	
	IDDOP(2)		• FmCF=10MHz ceramic oscillation mode • System clock set to 10MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 5.5		5.3	9.1	
				2.2 to 3.6		3.4	5.8	
	IDDOP(3)		• FmCF=4MHz ceramic oscillation mode • System clock set to 4MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 5.5		2.6	5.5	
				2.2 to 3.6		1.9	3.4	
	IDDOP(4)		• CF oscillation low amplifier size selected. (CFLAMP=1) • FmCF=4MHz ceramic oscillation mode • System clock set to 4MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/4 frequency division ratio	2.2 to 5.5		1.1	2.1	
				2.2 to 3.6		0.56	1.1	
	IDDOP(5)		• External FmCF oscillation stopped. • System clock set to internal medium speed RC oscillation. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	2.2 to 5.5		0.47	1.2	
				2.2 to 3.6		0.28	0.65	
	IDDOP(6)		• External FmCF oscillation stopped. • Internal medium speed RC oscillation stopped. • System clock set to 8MHz with frequency variable RC oscillation.(RCCTD=0) • 1/1 frequency division ratio.	2.7 to 5.5		4.2	8.1	
				2.7 to 3.6		3.3	5.6	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

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Parameter	Symbol	Pin/ Remarks	Conditions	Specification				
				V_{DD}[V]	min	typ	max	unit
HALT mode consumption current (Note 9-1) (Note 9-2)	IDDHALT(1)	V_{DD}1	• HALT mode • FmCF=12MHz ceramic oscillation mode • System clock set to 12MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 5.5		2.3	4.1	mA
				2.7 to 3.6		1.2	1.9	
	IDDHALT(2)		• HALT mode • FmCF=10MHz ceramic oscillation mode • System clock set to 10MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2to 5.5		1.9	3.4	
				2.2 to 3.6		1.0	1.6	
	IDDHALT(3)		• HALT mode • FmCF=4MHz ceramic oscillation mode • System clock set to 4MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 5.5		1.3	2.5	
				2.2 to 3.6		0.53	1.0	
	IDDHALT(4)		• HALT mode • CF oscillation low amplifier size selected. (CFLAMP=1) • FmCF=4MHz ceramic oscillation mode • System clock set to 4MHz side • Internal medium speed RC oscillation stopped. • Frequency variable RC oscillation stopped. • 1/4 frequency division ratio	2.2 to 5.5		0.80	1.5	
				2.2 to 3.6		0.31	0.62	
	IDDHALT(5)		• HALT mode • External FmCF oscillation stopped. • System clock set to internal medium speed RC oscillation • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	2.2 to 5.5		0.28	0.73	
				2.2 to 3.6		0.14	0.36	
	IDDHALT(6)		• HALT mode • External FmCF oscillation stopped. • Internal medium speed RC oscillation stopped. • System clock set to 8MHz with frequency variable RC oscillation. (RCCTD=0) • 1/1 frequency division ratio.	2.7 to 5.5		1.3	2.7	
				2.7 to 3.6		0.93	1.8	
HOLD mode consumption current (Note 9-1) (Note 9-2)	IDDHOLD(1)	V_{DD}1	HOLD mode • CF1=V_{DD} or open (External clock mode)	2.2 to 5.5		0.03	25	μA
				2.2 to 3.6		0.02	5.9	
	IDDHOLD(2)		HOLD mode • CF1=V_{DD} or open (External clock mode) • Ta=-10 to +50°C	5.0		0.03	1.2	
				3.3		0.02	0.56	
				2.5		0.01	0.40	
	IDDHOLD(3)		HOLD mode • CF1=V_{DD} or open (External clock mode) • LVD option selected	2.2 to 5.5		3.0	29	
				2.2 to 3.6		2.3	10	
	IDDHOLD(4)		HOLD mode • CF1=V_{DD} or open (External clock mode) • Ta=-10 to +50°C • LVD option selected	5.0		3.0	7.3	
				3.3		2.3	3.4	
				2.5		2.0	2.9	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

F-ROM Programming Characteristics at Ta = +10°C to +55°C, $V_{SS}1$ = 0V

Parameter	Symbol	Pin/Remarks	Conditions		Specification			
				V_{DD}[V]	min	typ	max	unit
Onboard programming current	IDDFW(1)	$V_{DD}1$	• Only current of the flash block.	2.2 to 5.5		5	10	mA
Programming time	tFW(1)		• Erasing time	2.2 to 5.5		20	30	ms
	tFW(2)		• Programming time			40	60	µs

Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

• CF oscillation normal amplifier size selected (CFLAMP=0)

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Nominal Frequency	Type	Oscillator Name	Circuit Constant				Operating Voltage Range [V]	Oscillation Stabilization Time		Remarks
			C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]		typ [ms]	max [ms]	
12MHz	SMD	CSTCE12M0G52-R0	(10)	(10)	Open	680	2.2 to 5.5	0.1	0.5	Internal C1,C2
					Open	1.0k	2.5 to 5.5	0.1	0.5	
10MHz	SMD	CSTCE10M0G52-R0	(10)	(10)	Open	680	2.0 to 5.5	0.1	0.5	
					Open	1.0k	2.1 to 5.5	0.1	0.5	
	LEAD	CSTLS10M0G53-B0	(15)	(15)	Open	680	2.2 to 5.5	0.1	0.5	
					Open	1.0k	2.4 to 5.5	0.1	0.5	
8MHz	SMD	CSTCE8M00G52-R0	(10)	(10)	Open	1.0k	1.9 to 5.5	0.1	0.5	
					Open	1.5k	2.0 to 5.5	0.1	0.5	
	LEAD	CSTLS8M00G53-B0	(15)	(15)	Open	1.0k	2.0 to 5.5	0.1	0.5	
					Open	1.5k	2.2 to 5.5	0.1	0.5	
6MHz	SMD	CSTCR6M00G53-R0	(15)	(15)	Open	1.5k	1.9 to 5.5	0.1	0.5	
					Open	2.2k	2.0 to 5.5	0.1	0.5	
	LEAD	CSTLS6M00G53-B0	(15)	(15)	Open	1.5k	2.0 to 5.5	0.1	0.5	
					Open	2.2k	2.1 to 5.5	0.1	0.5	
4MHz	SMD	CSTCR4M00G53-R0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.2	0.6	
					Open	3.3k	1.9 to 5.5	0.2	0.6	
	LEAD	CSTLS4M00G53-B0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.2	0.6	
					Open	3.3k	1.9 to 5.5	0.2	0.6	

• CF oscillation low amplifier size selected (CFLAMP=1)

■MURATA

Nominal Frequency	Type	Oscillator Name	Circuit Constant				Operating Voltage Range [V]	Oscillation Stabilization Time		Remarks
			C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]		typ [ms]	max [ms]	
4MHz	SMD	CSTCR4M00G53-R0	(15)	(15)	Open	1.0k	1.9 to 5.5	0.2	0.6	Internal C1,C2
					Open	2.2k	2.1 to 5.5	0.2	0.6	
		CSTCR4M00G53095-R0	(15)	(15)	Open	1.0k	1.8 to 5.5	0.2	0.6	
					Open	2.2k	1.9 to 5.5	0.2	0.6	
	LEAD	CSTLS4M00G53-B0	(15)	(15)	Open	1.0k	2.0 to 5.5	0.2	0.6	
					Open	2.2k	2.1 to 5.5	0.2	0.6	
		CSTLS4M00G53095-B0	(15)	(15)	Open	1.0k	1.8 to 5.5	0.2	0.6	
					Open	2.2k	1.9 to 5.5	0.2	0.6	

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 3).

- Time till the oscillation gets stabilized after the CPU reset state is released.
- Till the oscillation gets stabilized after the instruction for starting the main clock oscillation circuit is executed.
- Till the oscillation gets stabilized after the HOLD mode is reset.

(Notes on the implementation of the oscillator circuit)

- Oscillation is influenced by the circuit pattern layout of printed circuit board. Place the oscillation-related components as close to the CPU chip and to each other as possible with the shortest possible pattern length.
- Keep the signal lines whose state changes suddenly or in which large current flows as far away from the oscillator circuit as possible and make sure that they do not cross one another.
- Be sure to insert a current limiting resistor (Rd) so that the oscillation amplitude never exceeds the input voltage level that is specified as the absolute maximum rating.
- The oscillator circuit constants shown above are sample characteristic values that are measured using the Our designated oscillation evaluation board. Since the accuracy of the oscillation frequency and other characteristics vary according to the board on which the IC is installed, it is recommended that the user consult the resonator vendor for oscillation evaluation of the IC on a user's production board when using the IC for applications that require high oscillation accuracy. For further information, contact your resonator vendor or Our company Semiconductor sales representative serving your locality.
- It must be noted, when replacing the flash ROM version of a microcontroller with a mask ROM version, that their operating voltage ranges may differ even when the oscillation constant of the external oscillator is the same.

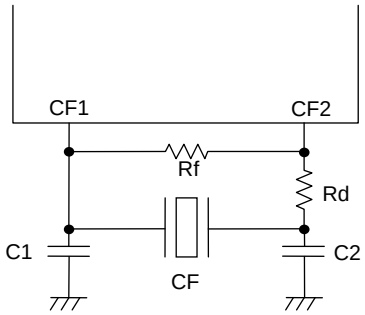


Figure 1 CF Oscillator Circuit

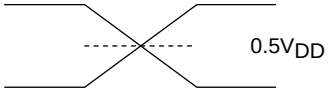
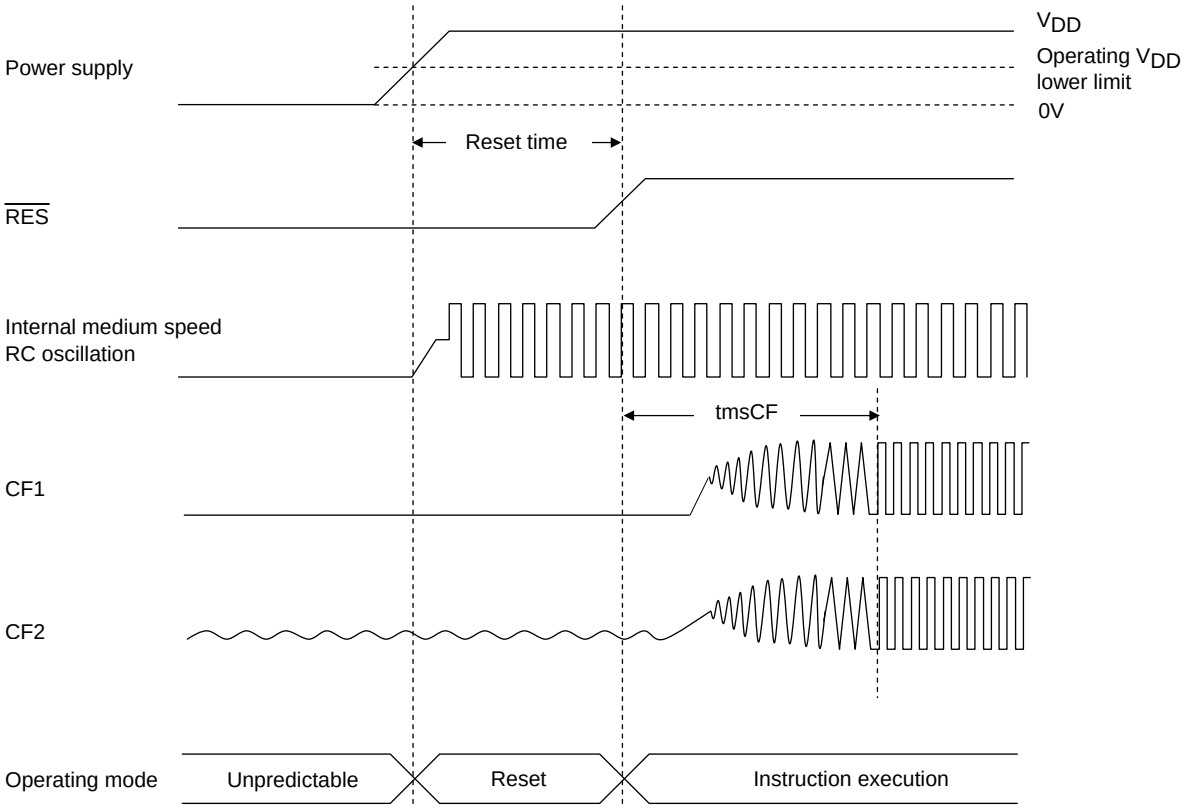
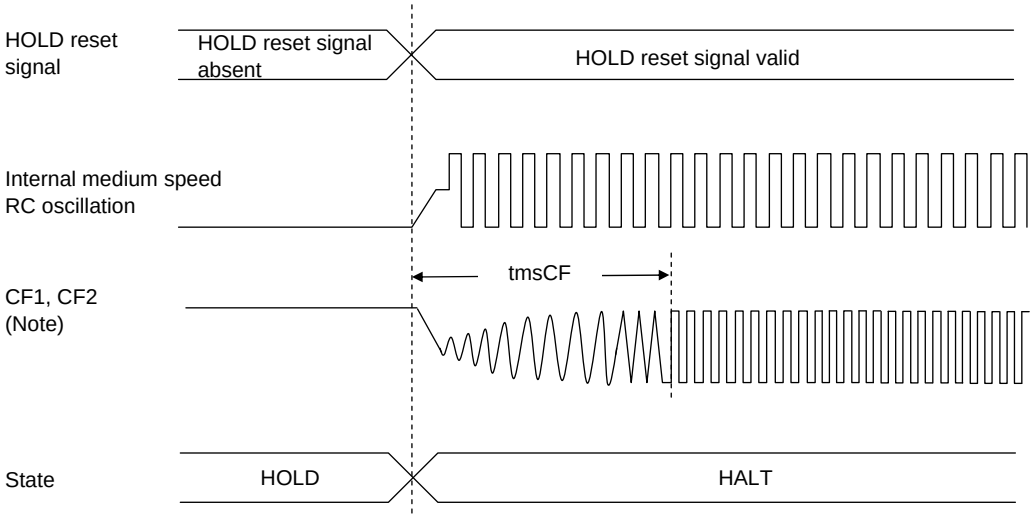


Figure 2 AC Timing Measurement Point



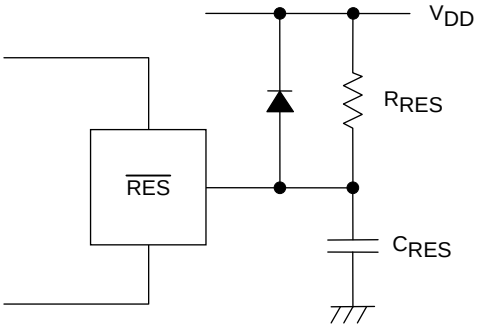
Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Note: External oscillation circuit is selected.

Figure 3 Oscillation Stabilization Times



Note:
External circuits for reset may vary depending on the usage of POR and LVD. Please refer to the user's manual for more information..

Figure 4 Reset Circuit

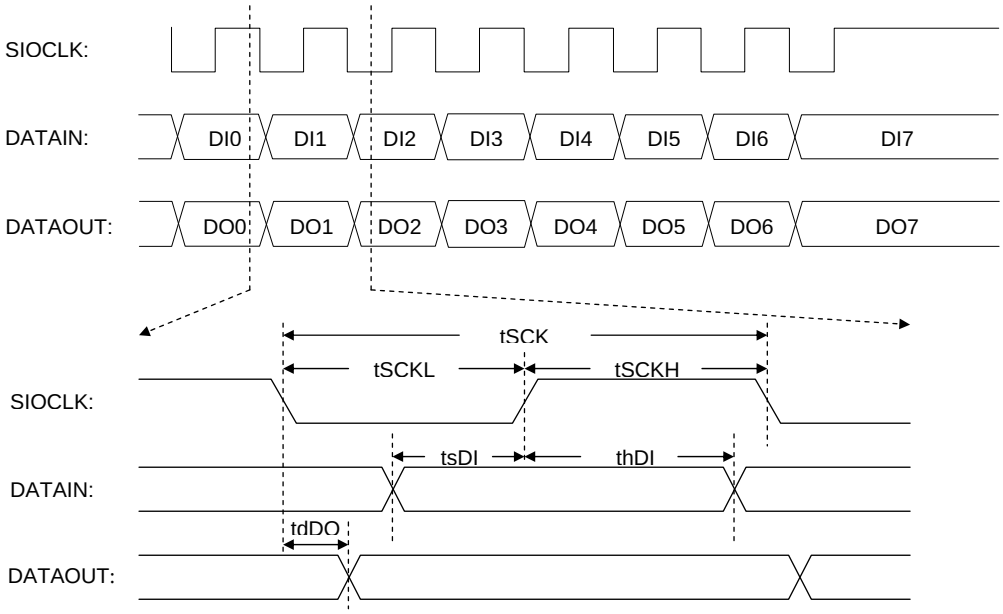


Figure 5 Serial I/O Output Waveforms

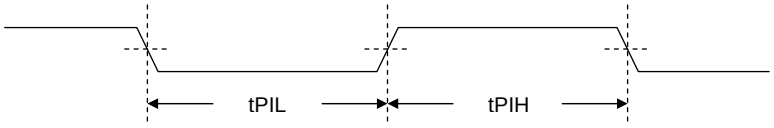


Figure 6 Pulse Input Timing Signal Waveform

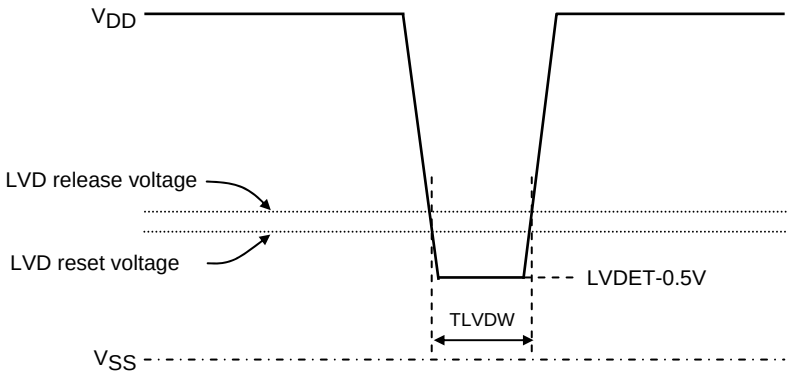


Figure 9 Low voltage detection minimum width
(Example of momentary power loss / Voltage variation waveform)